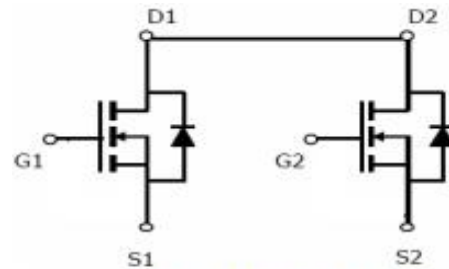




N-Channel Enhancement Mode Power MOSFET

The MX8203 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching applications.



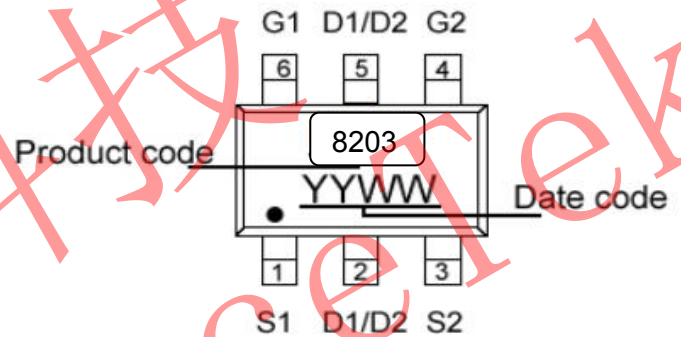
Schematic diagram

General Features

- ◆ $V_{DS} = 20V, I_D = 6A$
- ◆ $R_{DS(ON)}$ (Typ.) $16m\Omega @ V_{GS} = 4.5V$
- ◆ $R_{DS(ON)}$ (Typ.) $21m\Omega @ V_{GS} = 2.5V$
- ◆ High Power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface Mount Package

Applicatio

Battery protection
Load switch
Power management



Marking and pin assignment

Table 1. Absolute Maximum Ratings ($T_A = 25^\circ C$)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 10	V
Drain Current-Continuous	I_D	6	A
Drain Current-Pulsed (Note 1)	I_{DM}	25	A
Maximum Power Dissipation	P_D	1.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ C$



Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	83	$^{\circ}C/W$
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Electrical Characteristics (TA=25 $^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20	21	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=19.5V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.7	1.2	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=4.5A$	-	16	20	m Ω
		$V_{GS}=2.5V, I_D=3.5A$	-	21	28	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=4.5A$	-	10	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{iss}	$V_{DS}=8V, V_{GS}=0V,$ $F=1.0MHz$	-	600	-	PF
Output Capacitance	C_{oss}		-	330	-	PF
Reverse Transfer Capacitance	C_{rss}		-	140	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, I_D=1A,$ $V_{GS}=4.5V, R_G=6\Omega$	-	10	20	nS
Turn-on Rise Time	t_r		-	11	25	nS
Turn-Off Delay Time	$t_{d(off)}$		-	35	70	nS
Turn-Off Fall Time	t_f		-	30	60	nS
Total Gate Charge	Q_g	$V_{DS}=10V, I_D=4A,$ $V_{GS}=4.5V$	-	10	15	nC
Gate-Source Charge	Q_{gs}		-	2.3	-	nC
Gate-Drain Charge	Q_{gd}		-	1.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS}=0V, I_S=1.7A$	-	0.75	1.2	V
Diode Forward Current (Note 2)	I_S		-	-	1.7	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

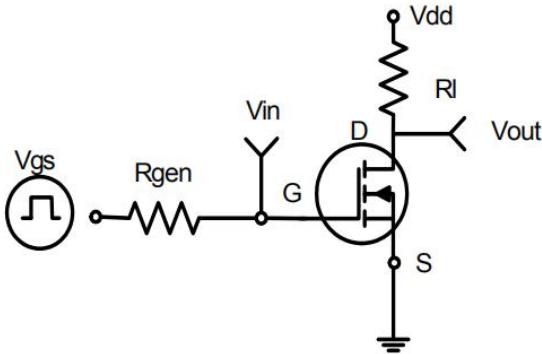


Figure 1: Switching Test Circuit

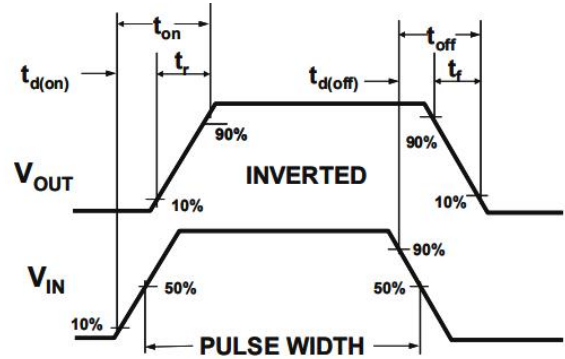


Figure 2: Switching Waveforms

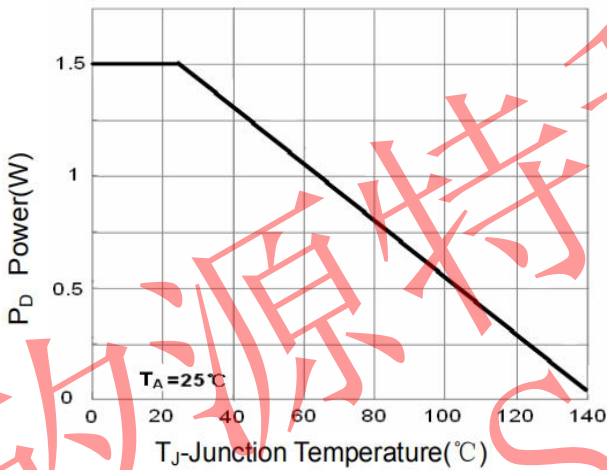


Figure 3 Power Dissipation

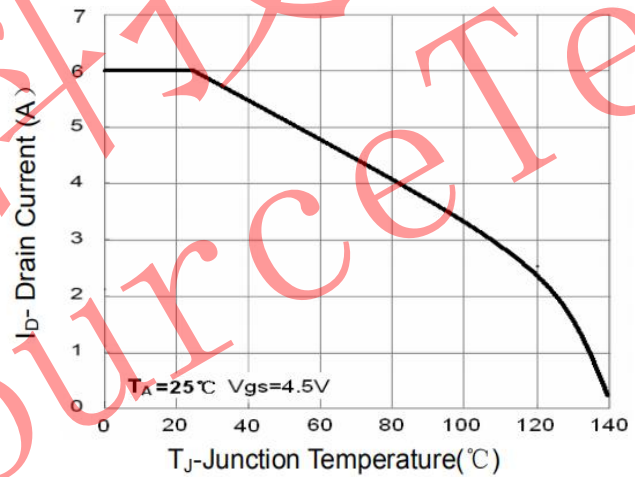


Figure 4 Drain Current

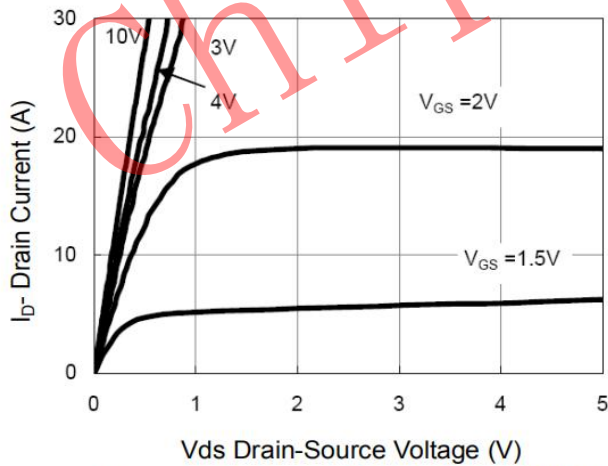


Figure 5 Output CHARACTERISTICS

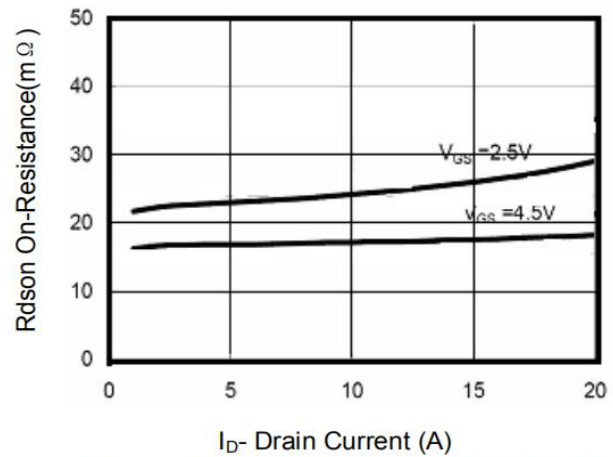


Figure 6 Drain-Source On-Resistance

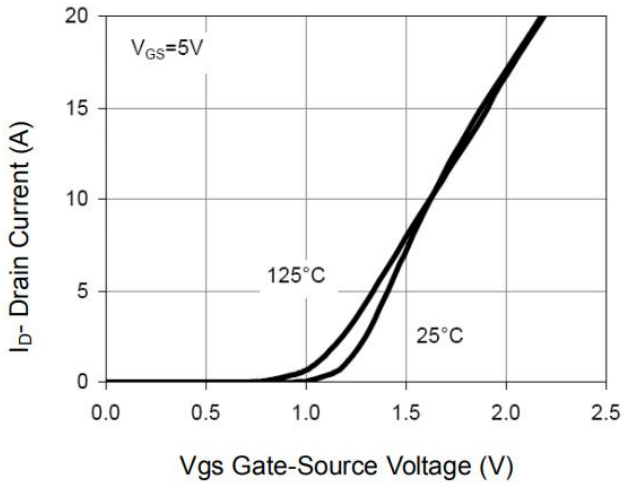


Figure 7 Transfer Characteristics

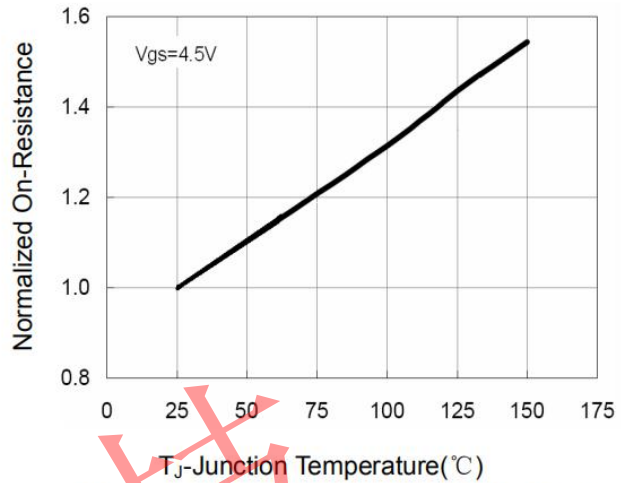


Figure 8 Drain-Source On-Resistance

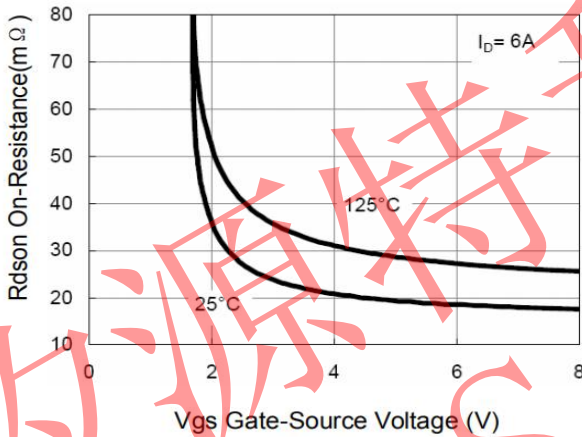


Figure 9 Rdson vs Vgs

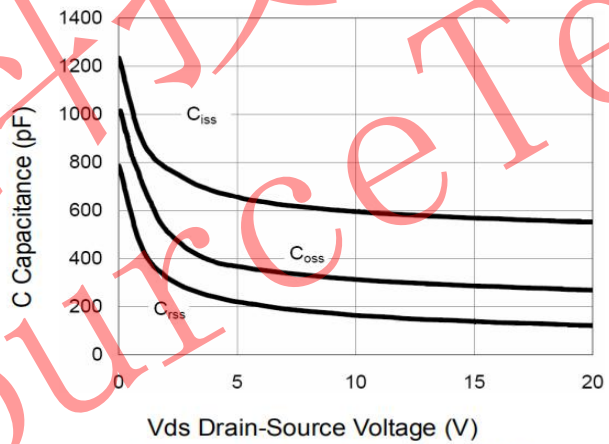


Figure 10 Capacitance vs Vds

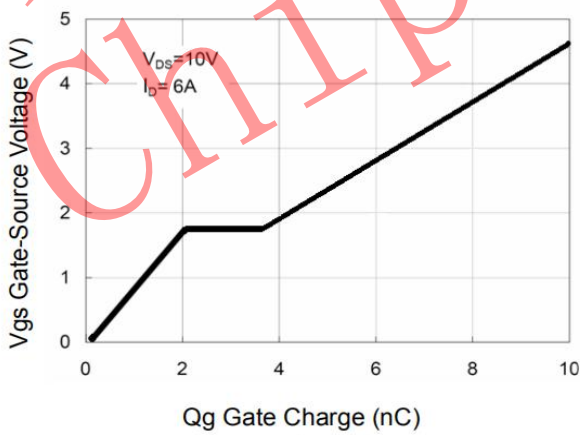


Figure 11 Gate Charge

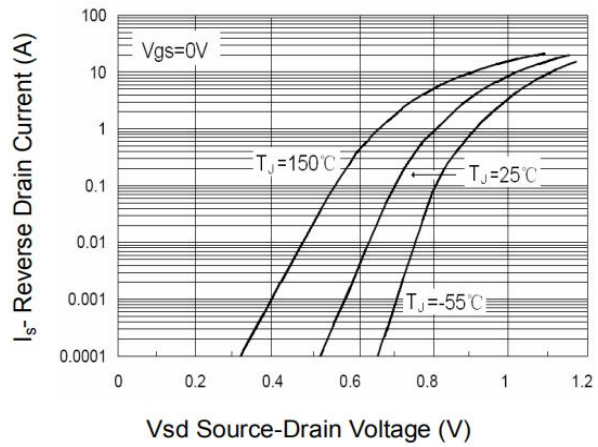


Figure 12 Source- Drain Diode Forward

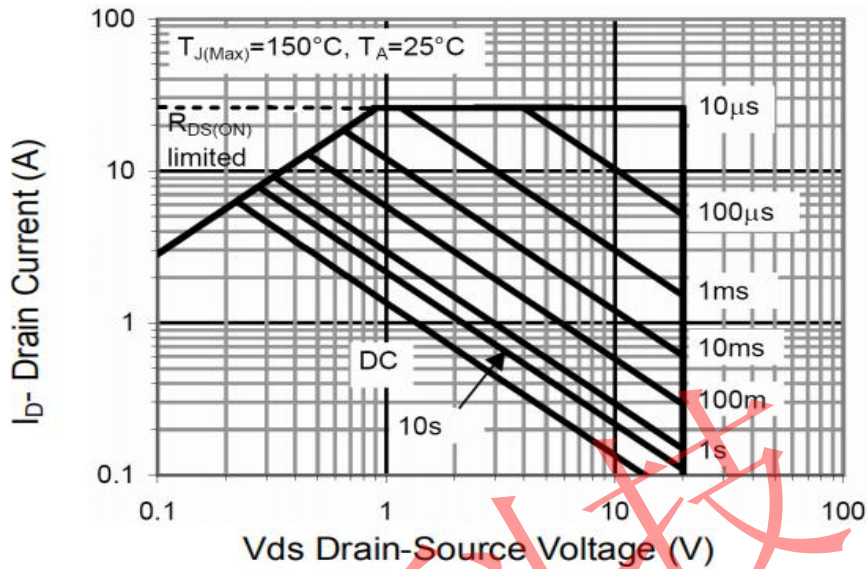


Figure 13 Safe Operation Area

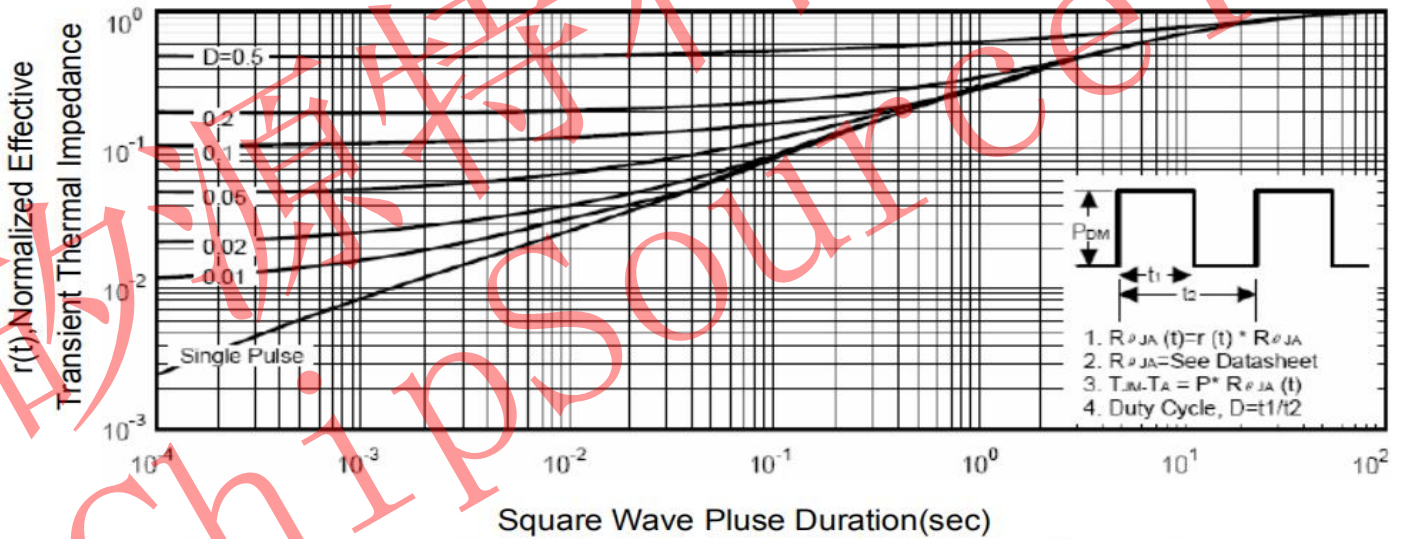
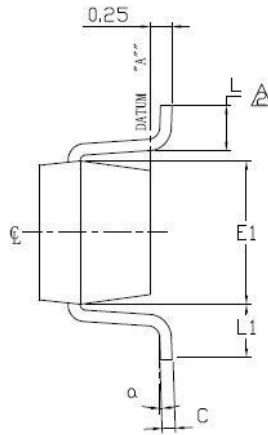
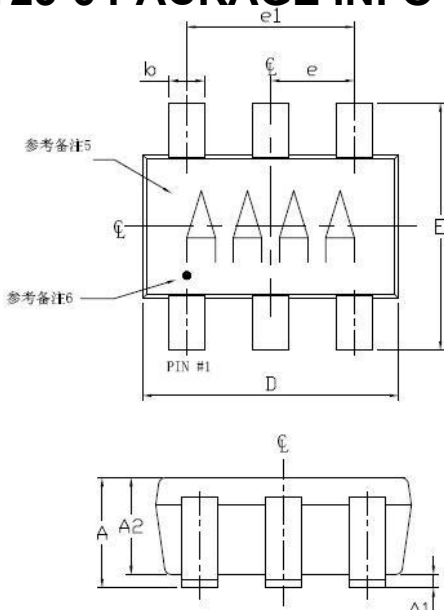


Figure 14 Normalized Maximum Transient Thermal Impedance



SOT23-6 PACKAGE INFO



SYMBOL	MIN	NOM	MAN
A	0.90	1.25	1.45
A1	0.00	0.05	0.15
A2	0.90	1.10	1.30
k	0.35	0.40	0.50
C	0.08	0.15	0.20
D	2.80	2.90	3.00
E	2.60	2.80	3.00
E1	1.50	1.625	1.75
L	0.35	0.45	0.60
L1	0.60 REF.		
e1	1.90 BSC.		
e	0.95 BSC.		
a	0°	2.5°	8°

PKG CODES:
U6-1, U6-2, U6-4, U6CN-2,
U6SN-1, U6F-6, U6FH-6

备注:

1. 标注单位:MM.
2. 引脚长度的测量点为引脚与塑封体接触点及引脚边缘最长处.
3. 塑封体测量尺寸不包括毛刺及金属毛刺,另塑封体毛刺及金属毛刺长度不超过0.25mm.
4. 引脚平面度控制小于0.1mm.
5. 印字面向上进行读取时, PIN1 位于左下方(参考图解).
6. PIN1的标记最小为 \varnothing 0.3mm,并位于PIN1脚位上方.
7. 考文献: JEDECT0236-VARIATION AB.